FAIRCHILD SEMICONDUCTOR

IPC ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard
http://www.ipc.org/IPC-175x

Form Type*
Distribute

Declaration Class*
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information

Company Name * **Fairchild Semiconductor**	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	**Response Date*** **Sat, May 26, 2012 02:03 AM**
Contact Name * **David Lancaster**	Title - Contact Product Ecology	**Phone - Contact *** **801-562-7455**	**Email - Contact *** **david.lancaster@fairchildsemi.com**
Authorized Representative * **David Lancaster**	Title - Representative Product Ecology	**Phone - Representative *** **801-562-7455**	Email - Representative * david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight***	UOM	Unit Type
74LCX257MTC	74LCX257MTC	TSSOP-16 (NiPdAu) (G)			INTERNAL PENANG	**0.056**	g	Each

Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Nickel/Palladium/Gold (Ni/Pd/Au)	CU Alloy	1	260 C	30 seconds	3

* Required Field

RoHS Material Composition Declaration	Declaration Type * Custom

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).

Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

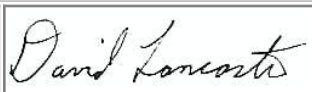
(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	Supplier Acceptance * Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2006/690/EC
0

Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

Homogeneous Material Composition Declaration for Electronic Products

Item/SubItem Name TSSOP-16 (NiPdAu) (G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.740	Supplier		Silicon	0.740	7440-21-3	13114
Die Attach	Other Organic Materials	0.083	Supplier		Resin	0.017	54208-63-8	296
			Supplier		Silver	0.067	7440-22-4	1182
Encapsulation	Thermoplastics	31.800	Supplier		Carbon Black	0.318	1333-86-4	5636
			Supplier		Epoxy Resin	6.360	29690-82-2	112713
			Supplier		Silica, vitreous	25.122	60676-86-0	445216
Lead Frame	Copper & its alloys	23.200	Supplier		Copper	22.300	7440-50-8	395204
			Supplier		Magnesium	0.035	7439-95-4	617
			B	Nickel (external applications only)	Nickel	0.742	7440-02-0	13150
			Supplier		Silicon	0.151	7440-21-3	2676
Plating	Precious metals	0.178	Supplier		Gold	0.003	7440-57-5	60
			B	Nickel (external applications only)	Nickel	0.170	7440-02-0	3013
			Supplier		Palladium	0.005	7440-05-3	88
Wire Bond	Precious metals	0.397	Supplier		Gold	0.397	7440-57-5	7036